

CDx4AC374、CDx4ACT374、CD74AC534 三态正边沿触发式八路 D 型触发器

1 特性

- 防 SCR 闩锁 CMOS 工艺和电路设计
- 双极 FAST^{*}/AS/S 的速度，同时功耗显著降低
- 平衡传播延迟
- 交流类型的工作电压范围为 1.5V 至 5.5V，并在电源电压的 30% 时具有平衡的抗噪性能
- $\pm 24\text{mA}$ 输出驱动电流
 - 扇出到 15 个 FAST^{*} IC
 - 驱动 50 Ω 传输线路

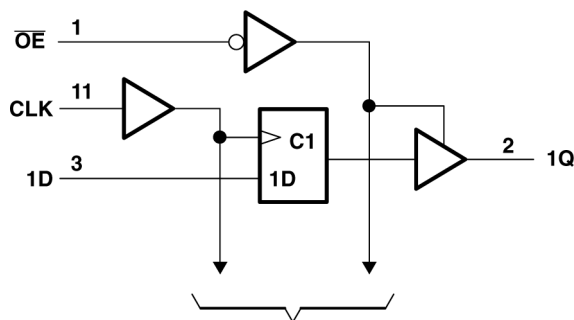
2 说明

AC374 器件的八个触发器是边沿触发式 D 型触发器。在时钟 (CLK) 输入发生正转换时，Q 输出被设置为在数据 (D) 输入端设置的逻辑电平。

器件信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾	本体尺寸 ⁽³⁾
CDx4AC/ACT374, CD74AC534	DW (SOIC, 20)	12.80mm x 10.3mm	12.80mm x 7.50mm
	N (PDIP, 20)	24.33mm x 9.4mm	24.33mm x 6.35mm

- (1) 有关更多信息，请参阅第 10 节。
- (2) 封装尺寸 (长 × 宽) 为标称值，并包括引脚 (如适用)。
- (3) 本体尺寸 (长 × 宽) 为标称值，不包括引脚。



To Seven Other Channels
逻辑图 (正逻辑)

* FAST 是 Fairchild Semiconductor Corp. 的注册商标。



Table of Contents

1 特性	1	6.2 Functional Block Diagram.....	11
2 说明	1	6.3 Device Functional Modes.....	11
3 Pin Configuration and Functions	3	7 Application and Implementation	12
4 Specifications	4	7.1 Typical Application.....	12
4.1 Absolute Maximum Ratings.....	4	7.2 Power Supply Recommendations.....	12
4.2 ESD Ratings.....	4	7.3 Layout.....	13
4.3 Recommended Operating Conditions:.....	4	8 Device and Documentation Support	14
4.4 Thermal Information.....	4	8.1 Documentation Support (Analog).....	14
4.5 Electrical Characteristics: AC Series.....	5	8.2 接收文档更新通知.....	14
4.6 Electrical Characteristics: ACT Series.....	5	8.3 支持资源.....	14
4.7 Prerequisite for Switching: AC Series.....	6	8.4 Trademarks.....	14
4.8 Switching Characteristics: AC Series.....	7	8.5 静电放电警告.....	14
4.9 Prerequisite for Switching: ACT Series.....	7	8.6 术语表.....	14
4.10 Switching Characteristics: ACT Series.....	7	9 Revision History	14
5 Parameter Measurement Information	9	10 Mechanical, Packaging, and Orderable Information	15
6 Detailed Description	11		
6.1 Overview.....	11		

3 Pin Configuration and Functions

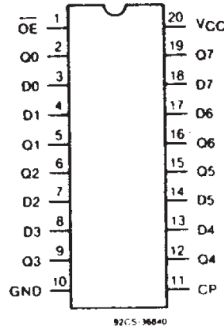


图 3-1. CDx4AC/ACT374, CD74AC534

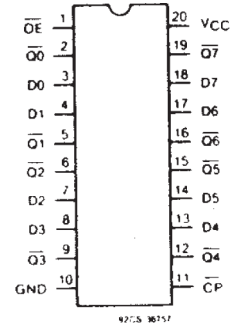


图 3-2. CDx4AC/ACT374, CD74AC534

表 3-1. Pin Functions

PIN		TYPE	DESCRIPTION
NAME	NO.		
OE	1	I	Enable pin
1Q	2	O	Output 1
1D	3	I	Input 1
2D	4	I	Input 2
2Q	5	O	Output 2
3Q	6	O	Output 3
3D	7	I	Input 3
4D	8	I	Input 4
4Q	9	O	Output 4
GND	10	-	Ground pin
CLK	11	I	Clock pin
5Q	12	O	Output 5
5D	13	I	Input 5
6D	14	I	Input 6
6Q	15	O	Output 6
7Q	16	O	Output 7
7D	17	I	Input 7
8D	18	I	Input 8
8Q	19	O	Output 8
V _{CC}	20	-	Power pin

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply-voltage	-0.5	6	V
I _{IK}	Input diode current (V _I < -0.5 V or V _I > V _{CC} ± 0.5 V)		±20	mA
I _{OK}	Output diode current (V _O < -0.5 V or V _O > V _{CC} + 0.5 V)		±50	mA
I _O	Output source or sink current per output pin (V _O > -0.5 V or V _O < V _{CC} + 0.5 V)		±50	mA
DC V _{CC} or ground current (I _{CC} or I _{GND})			±100	mA ⁽²⁾
T _{stg}	Storage temperature	-65	+150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) For up to 4 outputs per device; add ± 25 mA for each additional output.

4.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-0011	±2000	V

4.3 Recommended Operating Conditions:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	MIN	MAX	UNIT
V _{CC} ⁽¹⁾ Supply-Voltage Range: (For T _A = Full Package-Temperature Range)			
AC Types	1.5	5.5	V
ACT Types	4.5	5.5	V
V _I , V _O Input or Output Voltage	0	V _{CC}	V
T _A Operating Temperature	-55	+125	°C
dt/dv Input Rise and Fall Slew Rate			
at 1.5 V to 3 V (AC Types)	0	50	ns/V
at 3.6 V to 5.5 V (AC Types)	0	20	ns/V
at 4.5 V to 5.5 V (ACT Types)	0	10	ns/V

- (1) Unless otherwise specified, all voltages are referenced to ground.

4.4 Thermal Information

THERMAL METRIC ⁽¹⁾	CDx4AC/ACT374, CD74AC534		UNIT
	DW (SOIC)	N (PDIP)	
	20 PINS	20 PINS	
R _{θJA} Junction-to-ambient thermal resistance	101.2	50	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

4.5 Electrical Characteristics: AC Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNIT
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
V _{IH} High-Level Input Voltage			1.5	1.2	—	1.2	—	1.2	—	V
			3	2.1	—	2.1	—	2.1	—	
			5.5	3.85	—	3.85	—	3.85	—	
V _{IL} Low-Level Input Voltage			1.5	—	0.3	—	0.3	—	0.3	V
			3	—	0.9	—	0.9	—	0.9	
			5.5	—	1.65	—	1.65	—	1.65	
V _{OH} High-Level Output Voltage	V _{IH} or V _{IL} ⁽¹⁾ , ⁽²⁾	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
		-0.05	3	2.9	—	2.9	—	2.9	—	
		-0.05	4.5	4.4	—	4.4	—	4.4	—	
		-4	3	2.58	—	2.48	—	2.4	—	
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
V _{OH} Low-Level Output Voltage	V _{IH} or V _{IL} ⁽¹⁾ , ⁽²⁾	0.05	1.5	—	0.1	—	0.1	—	0.1	V
		0.05	3	—	0.1	—	0.1	—	0.1	
		0.05	4.5	—	0.1	—	0.1	—	0.1	
		12	3	—	0.36	—	0.44	—	0.5	
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
I _I Input Leakage Current	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
I _{OZ} 3-State Leakage Current	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
I _{CC} Quiescent Supply Current, MSI	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA

- (1) Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
(2) Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

4.6 Electrical Characteristics: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNIT
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
V _{IH} High-Level Input Voltage			4.5 to 5.5	2	—	2	—	2	—	V
V _{IL} Low-Level Input Voltage			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
V _{OH} High-Level Output Voltage	V _{IH} or V _{IL} ⁽¹⁾ , ⁽²⁾	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNIT
				+25		-40 to +85		-55 to +125		
	V _I (V)	I _O (mA)		MIN	MAX	MIN	MAX	MIN	MAX	
V _{OL} Low-Level Output Voltage	V _{IH} or V _{IL} (1), (2)	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
I _I Input Leakage Current	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μ A
I _{OZ} 3-State Leakage Current	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μ A
I _{CC} Quiescent Supply Current, MSI	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μ A
Δ I _{CC} Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load	V _{CC} -2.1		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

- (1) Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.
 (2) Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C. 75 ohms at + 125°C.

Act Input Loading Table

INPUT	UNIT LOADS ⁽²⁾
D, OE	0.7
CP	1.17

4.7 Prerequisite for Switching: AC Series

CHARACTERISTICS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNIT
			-40 to +85		-55 to +125		
			MIN	MAX	MIN	MAX	
t _w	Clock Pulse Width	1.5	44	—	50	—	ns
		3.3 ⁽¹⁾	4.9	—	5.6	—	
		5 ⁽²⁾	3.5	—	4	—	
t _{SU}	Setup Time Data to Clock	1.5	2	—	2	—	ns
		3.3	2	—	2	—	
		5	2	—	2	—	
t _H	Hold Time Data to Clock	1.5	2	—	2	—	ns
		3.3	2	—	2	—	
		5	2	—	2	—	
f _{MAX}	Maximum Clock Frequency	1.5	11	—	10	—	MHz
		3.3	101	—	89	—	
		5	143	—	125	—	

- (1) 3.3 V: min. is @ 3 V
 (2) 5 V: min. is @ 4.5 V

4.8 Switching Characteristics: AC Series

$t_r, t_f = 3 \text{ ns}, C_L = 50 \text{ pF}$

SYMBOL	CHARACTERISTICS	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNIT
			-40 to +85		-55 to +125		
			MIN	MAX	MIN	MAX	
t _{PLH} , t _{PHL}	Propagation Delays: Clock to Q AC374	1.5	—	123	—	135	ns
		3.3 ⁽¹⁾	3.9	13.7	3.8	15.1	
		5 ⁽²⁾	2.8	9.8	2.7	10.8	
t _{PLH} , t _{PHL}	Clock to \bar{Q} AC534	1.5	—	128	—	141	ns
		3.3	4.1	14.4	4	15.8	
		5	2.9	10.3	2.8	11.3	
t _{PLH} , t _{PZH}	Output Enable to Q, \bar{Q}	1.5	—	165	—	181	ns
		3.3	5.6	19.8	5.5	21.8	
		5	3.7	13.2	3.6	14.5	
t _{PLZ} , t _{PHZ}	Output Disable to Q, \bar{Q}	1.5	—	165	—	181	ns
		3.3	4.7	16.5	4.5	18.1	
		5	3.7	13.2	3.6	14.5	
C _{PD} ⁽³⁾	Power Dissipation Capacitance	—	67 Typ.		67 Typ.		pF
V _{OHV}	Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	5	4 Typ. @ 25°C				V
	Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	5	1 Typ. @25°C				V
C _I	Input Capacitance	—	—	10	—	10	pF
C _O	3-State Output Capacitance	—	—	15	—	15	pF

- (1) 3.3V: min. is @ 3.6 V
(2) 5 V: min. is @ 5.5 V
(3) C_{PD} is used to determine the dynamic power consumption, per flip flop.

4.9 Prerequisite for Switching: ACT Series

SYMBOL	CHARACTERISTICS	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNIT
			-40 to +85		-55 to +125		
			MIN	MAX	MIN	MAX	
t _W	Clock Pulse Width	5 ⁽¹⁾	3.9	—	4.5	—	ns
t _{SU}	Setup Time Data to Clock	5	2	—	2	—	ns
t _H	Hold Time Data to Clock	5	2.6	—	3	—	ns
f _{MAX}	Maximum Clock Frequency	5	125	—	110	—	MHz

- (1) 5 V: min. is @ 4.5 V

4.10 Switching Characteristics: ACT Series

over recommended operating free-air temperature range, ACT Series; $t_r, t_f = 3 \text{ ns}, C_L = 50 \text{ pF}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

SYMBOL	CHARACTERISTICS	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNIT
			-40 to +85		-55 to +125		
			MIN	MAX	MIN	MAX	
t _{PLH} , t _{PHL}	Propagation Delays: Clock to Q ACT374	5 ⁽¹⁾	2.9	10.2	2.8	11.2	ns
t _{PLH} , t _{PHL}	Clock to \bar{Q} ACT534	5	3	10.6	2.9	11.7	ns

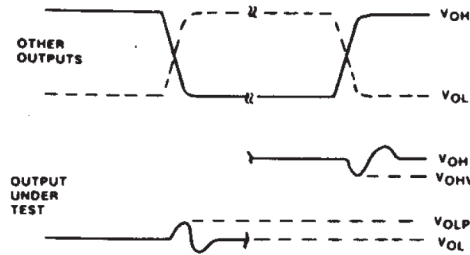
over recommended operating free-air temperature range, ACT Series; $t_r, t_f = 3$ ns, $C_L = 50$ pF (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

SYMBOL	CHARACTERISTICS	V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C				UNIT
			-40 to +85		-55 to +125		
			MIN	MAX	MIN	MAX	
$t_{PLZ}, t_{PHZ}, t_{PZL}, t_{PZH}$	Output Enable and Disable to Q ACT374	5	3.7	13.2	3.6	14.5	ns
$t_{PLZ}, t_{PHZ}, t_{PZL}, t_{PZH}$	Output Enable and Disable to \bar{Q} ACT534	5	3.7	13.2	3.6	14.5	ns
C_{PD} ⁽²⁾	Power Dissipation Capacitance	—	67 Typ.		67 Typ.		pF
V_{OHV}	Min. (Valley) V_{OH} During Switching of Other Outputs (Output Under Test Not Switching)	5	4 Typ. @ 25°C				V
V_{OLP}	Max. (Peak) V_{OL} During Switching of Other Outputs (Output Under Test Not Switching)	5	1 Typ. @25°C				V
C_I	Input Capacitance	—	—	10	—	10	pF
C_O	3-State Output Capacitance	—	—	15	—	15	pF

(1) 5V: min. is @ 5.5 V

(2) C_{PD} is used to determine the dynamic power consumption, per flip flop.

5 Parameter Measurement Information



- A. $1 V_{OHV}$ AND V_{OLP} ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
- B. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS: $PRR \leq 1$ MHz, $t_f = 3$ ns, $t_r = 3$ ns, SKEW 1 ns.
- C. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. I_C SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH $0.1 \mu F$ CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH
- D. 92CS-42406

图 5-1. Simultaneous Switching Transient Waveforms.

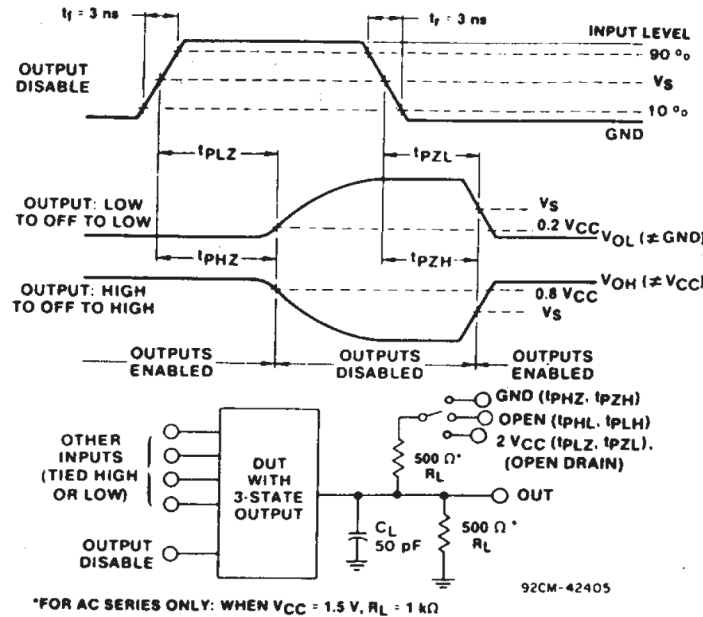


图 5-2. Three-state Propagation Delay Waveforms and Test Circuit.

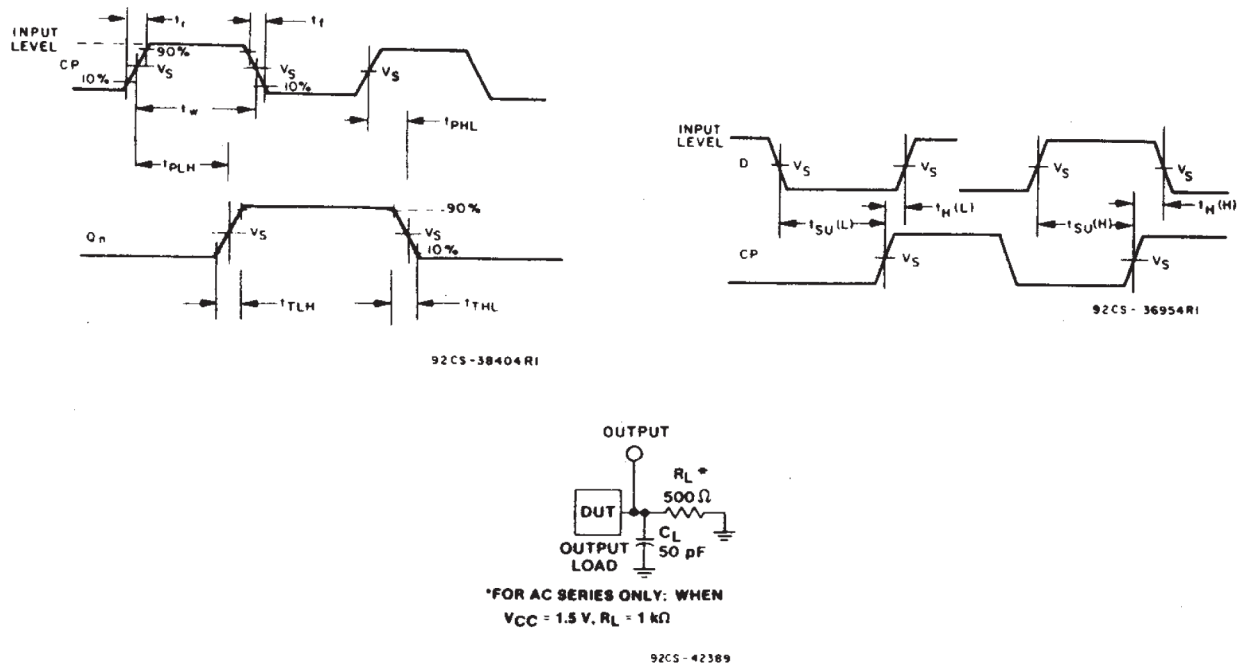


图 5-3. Propagation Delay Times and Test Circuit.

	CDx4AC	CDx4ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, V_S	$0.5 V_{CC}$	$0.5 V_{CC}$

6 Detailed Description

6.1 Overview

The eight flip-flops of the ' AC374 devices are D-type edge-triggered flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines in bus-organized systems without need for interface or pullup components.

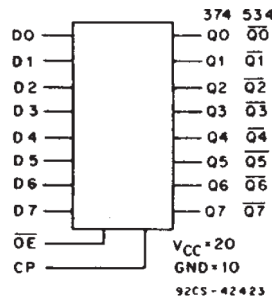
\overline{OE} does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The RCA-CD54/74AC374 and CD54/74AC534 and the CD54/74ACT374 and CD54/74ACT534 octal D-type, 3-state, positive-edge triggered flip-flops use the RCA ADVANCED CMOS technology. The eight flip-flops enter data into their registers on the LOW-to-HIGH transition of the clock (CP). The Output Enable (\overline{OE}) controls the 3-state outputs and is independent of the register operation. When the Output Enable (\overline{OE}) is HIGH, the outputs are in the high-impedance state. The CD54/74AC/ACT374 and CD54/74AC/ACT534 share the same pin configurations, but the CD54/74AC/ACT374 outputs are non-inverted while the CD54/74AC/ACT534 devices have inverted outputs. (For flow-through pin configurations, see CD54/74AC/ACT564 and CD54/74AC/ACT574.)

The CD74AC/ACT374 and CD74AC/ACT534 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to 70°C); Industrial (-40 to +85°C); and Extended Industrial/Military (-55 to +125°C).

The CD54AC/ACT374 and CD54AC/ACT534, available in chip form (H suffix), are operable over the -55 to +125°C temperature range.

6.2 Functional Block Diagram



6.3 Device Functional Modes

表 6-1. Truth Table

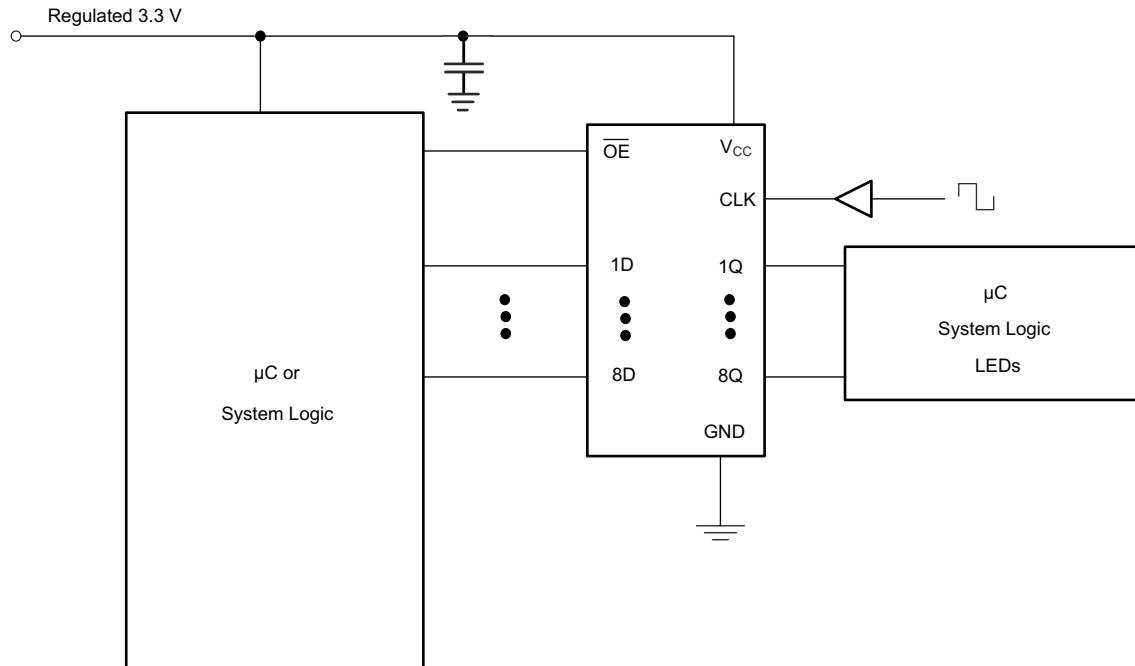
INPUTS			OUTPUTS	
			374	534
\overline{OE}	CP	Dn	Qn	\overline{Qn}
L		H	H	L
L		L	L	H
L	L	X	Q0	Q0
H	X	X	Z	Z

7 Application and Implementation

备注

以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

7.1 Typical Application



7.1.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

7.1.2 Detailed Design Procedure

1. Recommended Input conditions
 - Rise time and fall time specs: See ($\Delta t / \Delta V$) in [Recommended Operating Conditions](#) table.
 - Specified high and low levels: See (V_{IH} and V_{IL}) in [Recommended Operating Conditions](#) table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
2. Recommend output conditions
 - Load currents should not exceed 50 mA per output and 100 mA total for the part.
 - Outputs should not be pulled above V_{CC} .

7.2 Power Supply Recommendations

The power supply can be any voltage between the min and max supply voltage rating located in [节 4.3](#).

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends 0.1 μF and if there are multiple V_{CC} terminals, then TI recommends .01 μF or .022 μF for each power terminal. It is okay to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

7.3 Layout

7.3.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float. In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O' s so they also cannot float when disabled.

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
CD54AC374	Click here	Click here	Click here	Click here	Click here
CD74AC374	Click here	Click here	Click here	Click here	Click here
CD54ACT374	Click here	Click here	Click here	Click here	Click here
CD74ACT374	Click here	Click here	Click here	Click here	Click here
CD74AC534	Click here	Click here	Click here	Click here	Click here

8.2 接收文档更新通知

要接收文档更新通知，请导航至 ti.com 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

8.3 支持资源

[TI E2E™ 中文支持论坛](#) 是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [使用条款](#)。

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

所有商标均为其各自所有者的财产。

8.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

8.6 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

9 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (December 1998) to Revision A (March 2024)	Page
• 添加了 器件信息表 、 引脚功能表 、 ESD 等级表 、 热性能信息表 、 器件功能模式 、 应用和实施部分 、 器件和文档支持部分 以及 机械、封装和可订购信息部分	1
• Updated R ^θ JA values: DW = 40 to 101.2, all values in °C/W	4

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

重要声明和免责声明

TI“按原样”提供技术和可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证没有瑕疵且不做任何明示或暗示的担保，包括但不限于对适销性、某特定用途方面的适用性或不侵犯任何第三方知识产权的暗示担保。

这些资源可供使用 TI 产品进行设计的熟练开发人员使用。您将自行承担以下全部责任：(1) 针对您的应用选择合适的 TI 产品，(2) 设计、验证并测试您的应用，(3) 确保您的应用满足相应标准以及任何其他功能安全、信息安全、监管或其他要求。

这些资源如有变更，恕不另行通知。TI 授权您仅可将这些资源用于研发本资源所述的 TI 产品的应用。严禁对这些资源进行其他复制或展示。您无权使用任何其他 TI 知识产权或任何第三方知识产权。您应全额赔偿因在这些资源的使用中对 TI 及其代表造成的任何索赔、损害、成本、损失和债务，TI 对此概不负责。

TI 提供的产品受 [TI 的销售条款](#) 或 [ti.com](#) 上其他适用条款/TI 产品随附的其他适用条款的约束。TI 提供这些资源并不会扩展或以其他方式更改 TI 针对 TI 产品发布的适用的担保或担保免责声明。

TI 反对并拒绝您可能提出的任何其他或不同的条款。

邮寄地址：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265

Copyright © 2024，德州仪器 (TI) 公司